

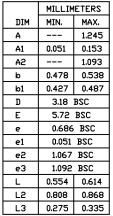


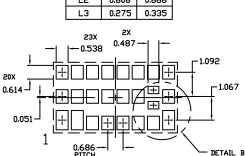
#### **SIP25, 5.72x3.18** CASE 127DZ ISSUE A

**DATE 06 DEC 2019** 

#### NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
- 2. CONTROLLING DIMENSION: MILLIMETERS
- COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE PADS.

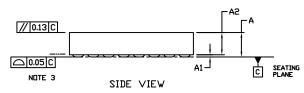


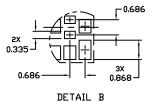


## RECOMMENDED MOUNTING FOOTPRINT

For additional information on our Pb-Free strategy and soldering details, please downloa the IN Seniconductor Soldering and Mounting Techniques Reference Manual, SILLDERRH/D.

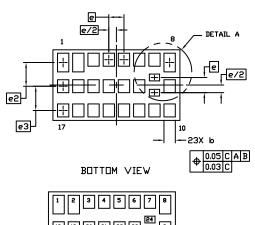
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3X L2

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B□TT□M VIEW PIN LAY□UT

# GENERIC MARKING DIAGRAM\*

XXXXXXXXXXX °

XXXX = Specific Device Code ZZZ = Assembly Lot Code \*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present. Some products may not follow the Generic Marking.

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DESCRIPTION:	SIP25, 5.72x3.18		PAGE 1 OF 1

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